

Title (en)

METHOD AND APPARATUS FOR WAFER METROLOGY

Title (de)

VERFAHREN UND VORRICHTUNG FÜR DIE MESSUNG AN WAFERN

Title (fr)

PROCEDE ET APPAREIL DE METROLOGIE DE PLAQUETTE

Publication

**EP 1163488 A1 20011219 (EN)**

Application

**EP 00921435 A 20000322**

Priority

- US 0007709 W 20000322
- US 12546299 P 19990322
- US 12891599 P 19990412
- US 14319999 P 19990709
- US 17285199 P 19991210
- US 49582100 A 20000201

Abstract (en)

[origin: WO0057127A1] This invention is an apparatus for imaging metrology, which in particular embodiments may be integrated with a processor station such that a metrology station is apart from but coupled to a process station. The metrology station is provided with a first imaging camera with a first field of view containing the measurement region. Alternate embodiments include a second imaging camera with a second field of view. Preferred embodiments comprise a broadband ultraviolet light source, although other embodiments may have a visible or near infrared light source of broad or narrow optical bandwidth. Embodiments including a broad bandwidth source typically include a spectrograph, or an imaging spectrograph. Particular embodiments may include curved, reflective optics or a measurement region wetted by a liquid. In a typical embodiment, the metrology station and the measurement region are configured to have 4 degrees of freedom of movement relative to each other.

IPC 1-7

**G01B 11/06**; **H01L 21/66**; **G01N 21/88**; **H01L 21/304**; **C23C 16/52**

IPC 8 full level

**B24B 49/12** (2006.01); **G01B 11/06** (2006.01); **G01B 11/24** (2006.01); **G01B 11/30** (2006.01); **G01N 21/95** (2006.01); **H01L 21/66** (2006.01); **H01L 21/67** (2006.01); **H01L 21/683** (2006.01); **G01N 21/21** (2006.01)

CPC (source: EP)

**B24B 49/12** (2013.01); **G01B 11/0625** (2013.01); **G01B 11/30** (2013.01); **G01N 21/9501** (2013.01); **H01L 21/67** (2013.01); **G01N 21/211** (2013.01); **H01L 22/12** (2013.01)

Citation (search report)

See references of WO 0057127A1

Citation (examination)

- US 4402613 A 19830906 - DALY JOHN K [US], et al
- US 4505585 A 19850319 - YOSHIKAWA SHOJI [JP], et al

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

**WO 0057127 A1 20000928**; **WO 0057127 A9 20020328**; AU 4175800 A 20001009; EP 1163488 A1 20011219; JP 2002540388 A 20021126; TW 493205 B 20020701

DOCDB simple family (application)

**US 0007709 W 20000322**; AU 4175800 A 20000322; EP 00921435 A 20000322; JP 2000606954 A 20000322; TW 89105382 A 20000322